

SOT1780-10

WLCSP36, wafer level chip-scale package, 36 terminals, 0.4 mm pitch, 2.8 mm x 2.52 mm x 0.5 mm body (backside coating included)

20 November 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP36
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	01-11-2018
Manufacturer package code	98ASA01327D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	2.8	-	mm
package width	-	2.52	-	mm
package height	-	0.5	-	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	36	-	



WLCSP36, wafer level chip-scale package, 36 terminals, 0.4 mm pitch, 2.8 mm x 2.52 mm x 0.5 mm body (backside coating included)

2 Package outline

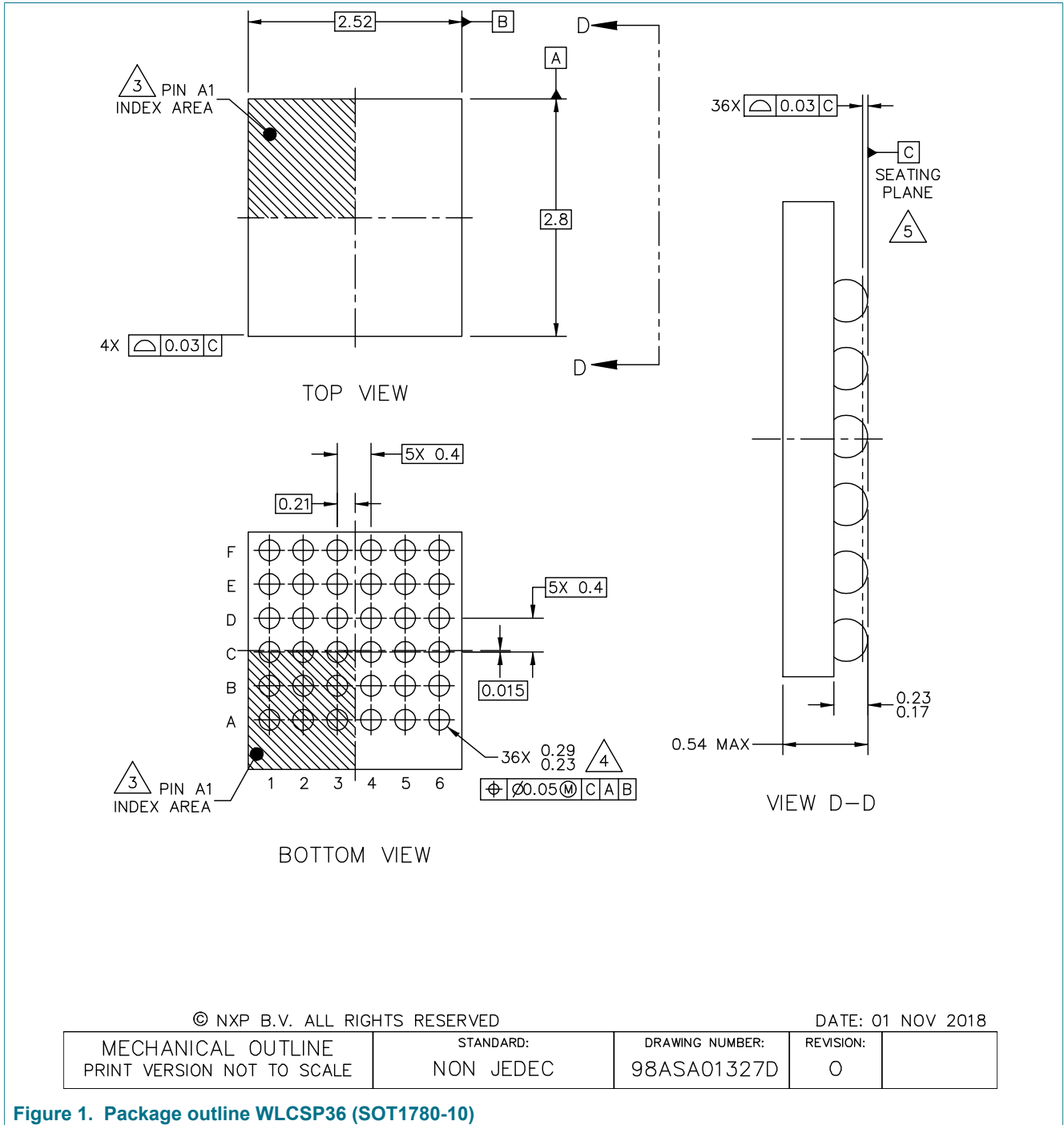


Figure 1. Package outline WLCSP36 (SOT1780-10)

WLCSP36, wafer level chip-scale package, 36 terminals, 0.4 mm pitch, 2.8 mm x 2.52 mm x 0.5 mm body (backside coating included)

3 Soldering

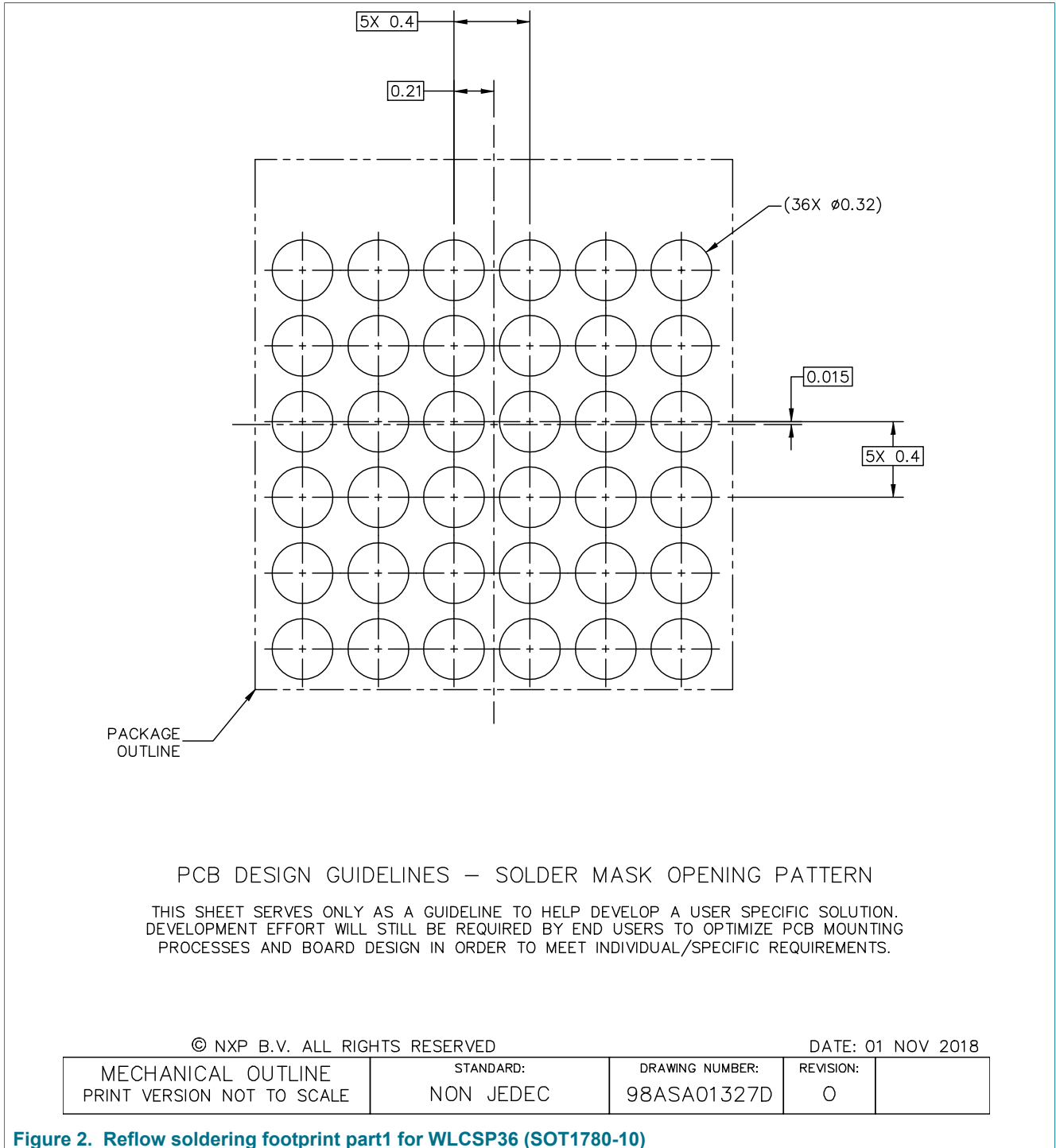


Figure 2. Reflow soldering footprint part1 for WLCSP36 (SOT1780-10)

WLCSP36, wafer level chip-scale package, 36 terminals, 0.4 mm pitch, 2.8 mm x 2.52 mm x 0.5 mm body (backside coating included)

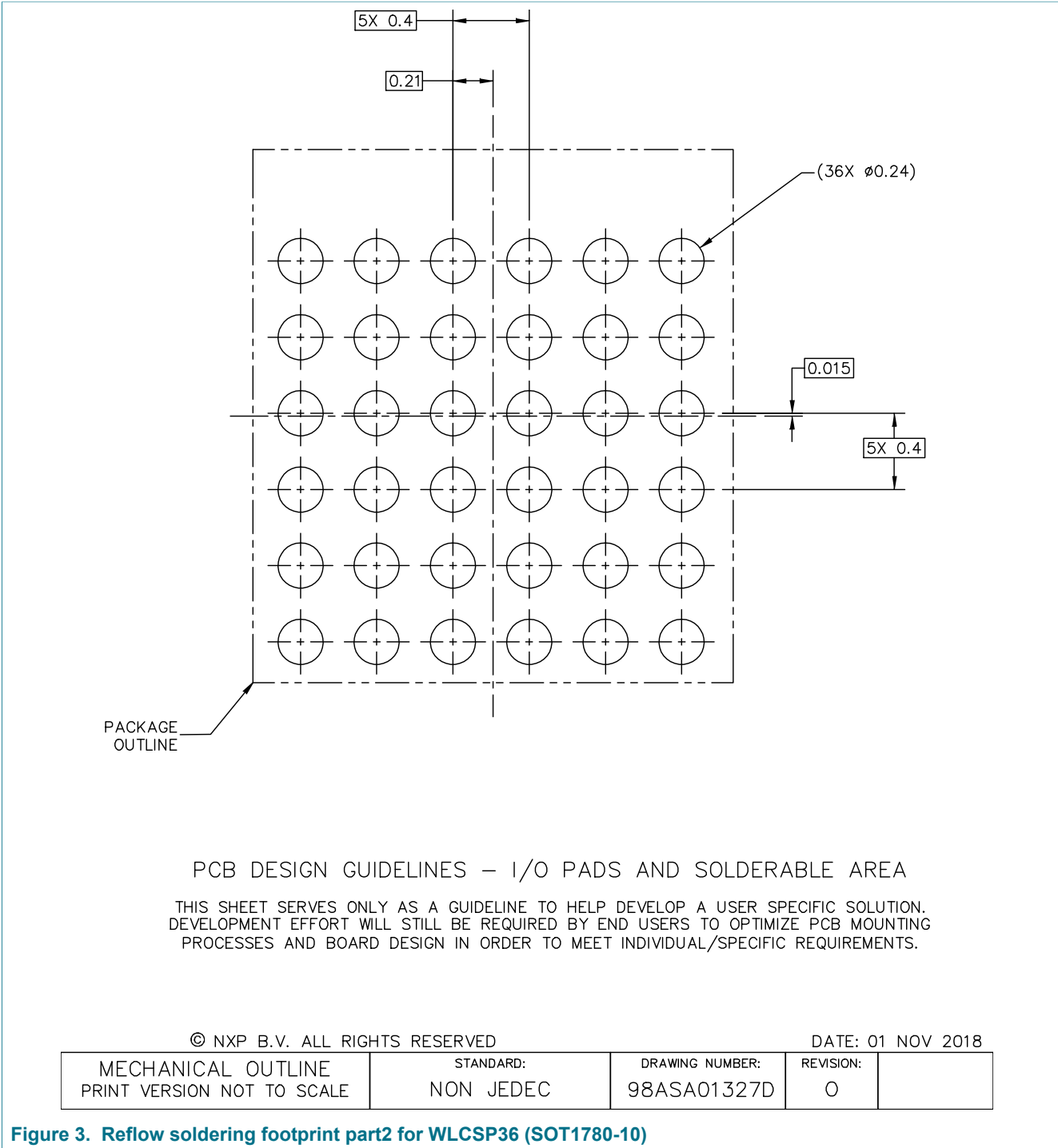


Figure 3. Reflow soldering footprint part2 for WLCSP36 (SOT1780-10)

WLCSP36, wafer level chip-scale package, 36 terminals, 0.4 mm pitch, 2.8 mm x 2.52 mm x 0.5 mm body (backside coating included)

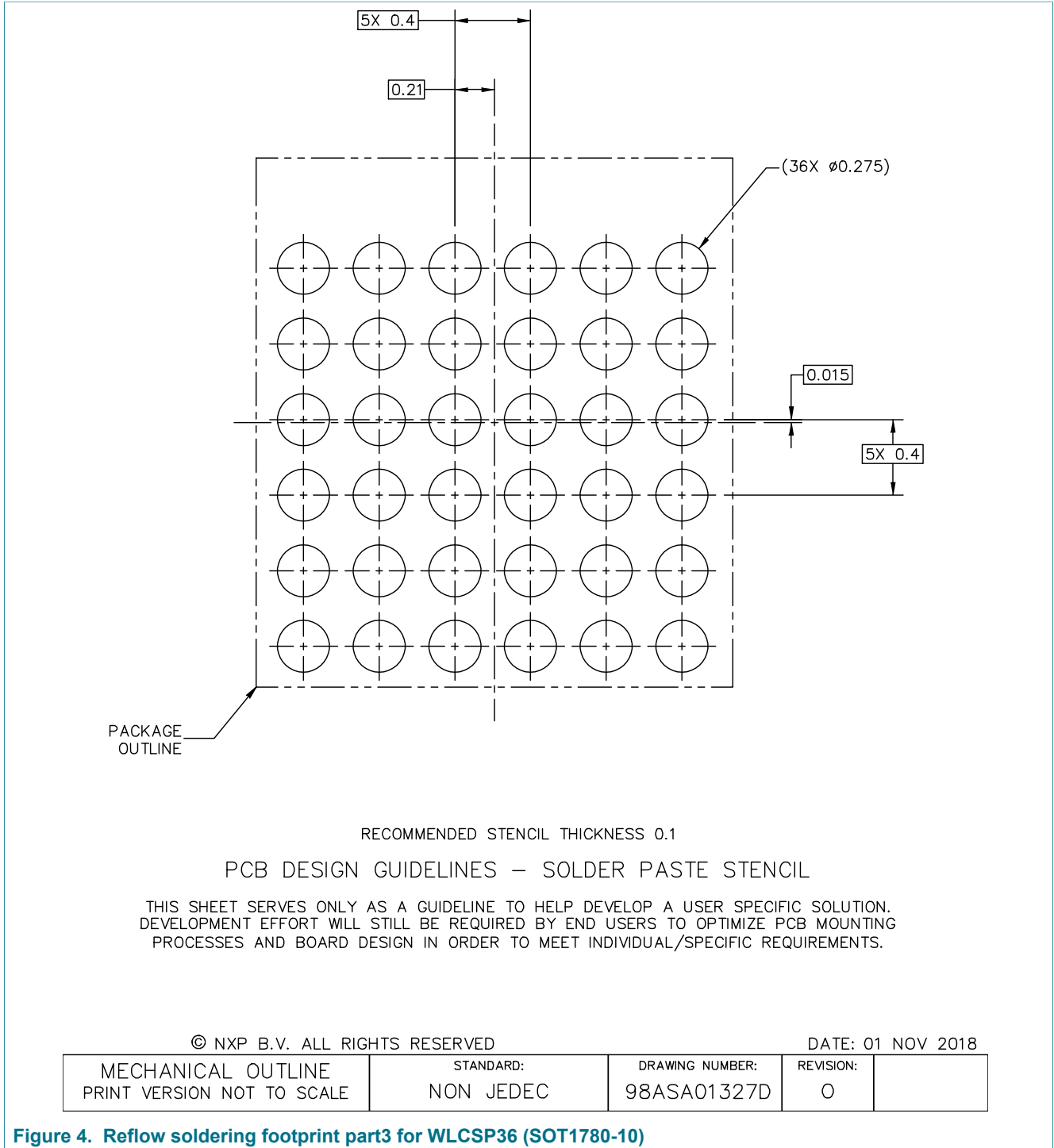


Figure 4. Reflow soldering footprint part3 for WLCSP36 (SOT1780-10)

WLCSP36, wafer level chip-scale package, 36 terminals, 0.4 mm pitch, 2.8 mm x 2.52 mm x 0.5 mm body
(backside coating included)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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DATE: 01 NOV 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01327D	REVISION: 0	
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Figure 5. Package outline note WLCSP36 (SOT1780-10)

4 Legal information

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